# BESS/EVI Application – TE solution





Li Xiang

**EVERY CONNECTION COUNTS** 



# EVI & BESS market overview





# **EVI PACK Solution 1**



# **BYD EVI PACK Solution**

#### **BYD EVI PACK Solution 2**



TAB 🧹

PCB terminal



# **EVI PACK Solution 3**





# **EVI PACK Summary**

#### **Application Snapshot**

#### **Key Trends**

- As a leader in electric vehicles & battery, BYD has ability to redesign the battery pack structure and integrate BDU, cell, and BMS to reduce the use of connectors, reduce the volume of battery packs and increase battery density to improve the battery life of electric vehicles. Therefore, it will become a trend to replace WTB connectors with metal structural parts.
- Connector with smaller size due to reduce pack volume
- Connector with high voltage due to increase the battery density

Product Suggest				
Application	DEVICE Product	Competitor		
Low voltage collection Temp. collection	Mini Dynamic Dynamic D1000 series PCB Terminal Metrimate	IRISO HRS JST Molex		
High voltage collection Heating system	Dynamic D3000 series Metrimate	HRS JST Molex		
Remark : If connector used in EV	PACK, it need to meet USCAR or L	V214 standard.		



# ESS(Household) PACK Solution

#### ESS PACK Solution 1





- ✓ ESS(Household) is composed by PACK and PCS
- ✓ Will use HDC connector to transmission the data between upper and lower battery modules
- ✓ Cell : Lithium iron phosphate battery(磷酸铁锂电 池)



# ESS(Household) PACK Solution

#### **ESS PACK Solution 2**









# **ESS(Household) PACK Solution**







# **ESS(Power) Solution**



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# ESS PACK Summary

#### **Application Snapshot**

Key Trends	Application	DEVICE Product	Competitor
<ul> <li>Reduce the use of connectors due to cost down requirement.</li> <li>Used connector with BTB type instead of WTB</li> <li>Connector with high voltage due to increase the battery density</li> </ul>	<ol> <li>Low voltage collection</li> <li>Temp. collection</li> <li>DC/DC</li> <li>Fan power &amp; data</li> </ol>	Mini Dynamic Dynamic D1000 series PCB Terminal Metrimate AMPMODU	IRISO HRS JST Molex Samtec
	<ol> <li>High voltage collection</li> <li>Power &amp; data</li> <li>Heating system</li> </ol>	Dynamic D3000 series Metrimate	HRS JST Molex

**Product Suggest** 



# **E-drive solution**

#### E-drive is mainly composed by drive unit and control unit

> Used our Dynamic D1000 series WTB solution for low voltage signal transmission in drive board.



Used ERNI SMC & MaxiBridge series WTB solution for low voltage signal transmission between driver board and control board.





# E-drive solution

- > Used Viola BTB solution for low voltage signal transmission between driver board and control board.
- > Used Dynamic D1000 series WTB solution for low voltage signal transmission in drive board.





# **E-drive Summary**

Application Snapshot		
Key Trends		
Mainly used WTB & BTB type connector		
Connector with smaller size due to reduce the		
volume in EV		

Application	<b>DEVICE Product</b>	Competitor	
1.Driver board and control board communication 2.External communication of the control board	Mini Dynamic Dynamic D1000 series MaxiBridge SMC Minibridge Viola	IRISO HRS JST Molex	
emark : Connector used in E-d	rive, it need to meet USCAR or L	/214 standard	



### **OBC** solution

#### OBC is usually composed by PFC unit, control unit and DC/DC unit. The main charging power of OBC is

#### 3.3kw,6.6kw and 11kw.

#### Remark: PFC mean power factor correction

Used ERNI Minibridge series 2/6/12pos WTB solution for low voltage signal transmission between control board and DC/DC board.





# **OBC Summary**

Application Snapshot		
Key Trends		
Mainly used WTB & BTB type connector		
Connector with smaller size due to reduce the		
volume in EV		

Application	DEVICE Product	Competitor
<ul><li>1.Communication between control board and DC/DC board</li><li>2.External communication of the control board</li></ul>	Mini Dynamic Dynamic D1000 series MaxiBridge SMC Minibridge Viola	IRISO HRS JST Molex
emark : Connector used in OB(	C, it need to meet USCAR or LV2	14 standard



# **Conclusion**

- For EV & ESS PACK, there are connector demand between cell unit and BIC, between BIC and BMU between BDU and BMU, heating system and BMU, cooling system and BMU.
- For E-drive, there are connector demand between driver board and control board, external communication of control board.
- For OBC, there are connector demand between control board and DC/DC board, external communication of control board.



# **Appendix**



# **Product Catalog**







AMPMODU Catalog





Metrimate Catalog







PDF



ERNI-MiniBridge





# ANY CONNECTION CAN CHANGE THE WORLD

**EVERY CONNECTION COUNTS**